ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES INDUSTRIES	C. Bannockł	ourn, Illinois, A	ll rights reserved utions.	Inder both This d	ocument parts, the	is a declaration en	n of the su compasses	bstances all lower	within the manufactu level materials for w	rer listed	tem. Note: nanufacture	if the item is an as r has engineering	sembly with lower responsibility.	
				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and I					ials and N	lfg Informa	tion		
Supplier Information														
Company name* Co		Company uni	Company unique ID			Unique ID Authority					Response Date*			
onsemi										2024-05	2024-05-17			
ontact Name Title - Contac			ontact J			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title			Title - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards	Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	n Number	Mfr Item Name		E	ffective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
	NCV815 TBG	NCV8154MW180250 Dual 300 mA, IBG		Low IQ, LDO, wettable flanks		024-05-17		Ν	MY1		23.85	mg	Each	
Manufacturing Proccess Informati	on													
Terminal Plating / Grid Array Mat	Cerminal Plating / Grid Array Material Terminal Base .		Alloy J-STD-020 MSL Rating		g	Peak Process Body Temperature Max Time at		e Max Time at Peak	ak Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260 C		С	30 seco		seconds 3			
Comments														
level 1 - maximum time at peak temperatur	e during so	ldering is 10-3	0 seconds											
For more information regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed									
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron		um and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ted Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of									
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted										
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all									
Exemption List Version	EL-2011/534/EU													
Declaration Signature														
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the									
Supplier Digital Signature Ra	stislav Drska	Le												

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.01	mg	Supplier	Silicon (Si)	7440-21-3		1.01	mg
Die Attach	0.12	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0072	mg
			Supplier	Silver (Ag)	7440-22-4		0.0978	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0072	mg
			Supplier	Misc.	Proprietary Data		0.0006	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0072	mg
Lead Frame	7.06	mg	Supplier	Tin (Sn)	7440-31-5		0.0176	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0155	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0176	mg
			Supplier	Copper (Cu)	7440-50-8		7.0092	mg
ead Frame plating	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.14	mg
Mold Compound-Black	14.2	mg		Epoxy resin	proprietary data		0.6674	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.42	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0142	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.431	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6674	mg
Plating	1.1	mg	Supplier	Tin (Sn)	7440-31-5		1.1	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5		0.22	mg